Cypress Semiconductor Corporation, 198 Champion Court, San Jose, CA 95134. Tel: (408) 943-2600

PRODUCT CHANGE NOTIFICATION

PCN: PCN172404 **Date:** June 18, 2017

Subject: Qualification of TI's DMOS6 as an Additional Wafer Fab Site and Cypress' Test 25 as an Additional Wafer Sort Site for the 128Kb/256Kb Automotive F-RAM Product Family

To: TOKYO ELECTRON DEVICE
TELDEVICE
cy-inside@teldevice.co.jp

Change Type: Major

Description of Change:
Cypress announces the qualification of TI's DMOS6 as an additional wafer fab site for the 128Kb/256Kb F-RAM automotive product family. This notice also announces the qualification of Cypress' Test 25 as an additional wafer sort site. Both changes are part of Cypress' flexible manufacturing initiative.

Benefit of Change:
Qualification of alternate manufacturing sites is part of the ongoing flexible manufacturing initiative announced by Cypress. The goal of the flexible manufacturing initiative is to provide the means for Cypress to continue to meet delivery commitments through dynamic, changing market conditions.

Part Numbers Affected: 8
See the attached 'Affected Parts List' file for a list of all part numbers affected by this change. Note that any new parts that are introduced after the publication of this PCN will include all changes outlined in this PCN.

Qualification Status:
This wafer fab site has been qualified through a series of tests documented in the Qualification Test Plan (QTP#155006). This wafer sort site has been qualified through a series of tests documented in the Qualification Test Plan (QTP# 170503). These qualification reports can be found as an attachment to this PCN or at the following locations:

QTP#155006
QTP#170503

Sample Status:
Qualification samples may not be built ahead of time for all part numbers affected by this change and may be subject to standard lead times. Please review the attached 'Affected Parts List' file for a list of affected part numbers with their associated sample ordering part numbers. If you require qualification samples, please contact your local Cypress sales representative as soon as possible, preferably within 30 days of the date of this PCN, to place any sample orders.

Approximate Implementation Date:
Effective April 4th 2018, all shipments of affected part numbers listed in the "Affected Parts List" file will be manufactured at either DMOS5 or DMOS6 and sorted at either KYEC or Test 25.

Anticipated Impact:
Products manufactured and sorted at the new sites are completely compatible with existing products from a functional, parametric, and quality performance perspective.

Cypress also recommends that customers take this opportunity to review these changes against current application notes, system design considerations and customer environment conditions to assess impact (if any) to their application.

Method of Identification:
Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package and through a revision letter on the die.

Response Required:
No response is required.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration